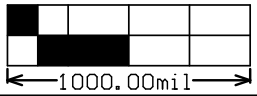
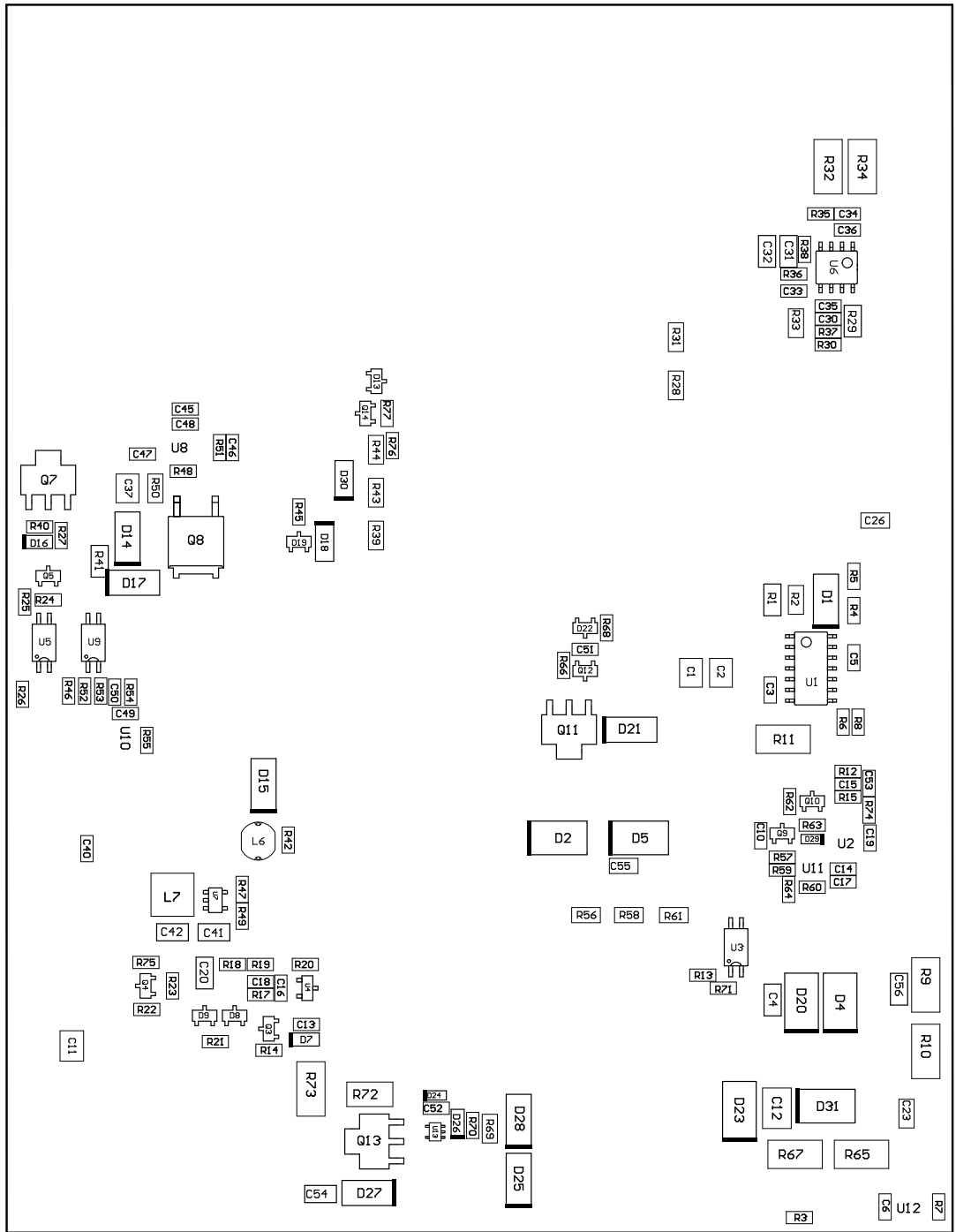


The reference design PMP10215 Rev-D has been built on PMP10215 Rev-B Board



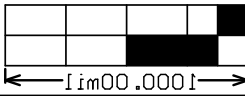
COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM TOP SIDE	BOARD #: PMP10215	REV: B	SUN REV: Not In VersionControl
M1 Board Outline	TID #: .TID		
PLOT NAME = Assembly Top	GENERATED : 4/26/2016	10:38:36 AM	TEXAS INSTRUMENTS



The reference design PMP10215 Rev-D has been built on PMP10215 Rev-B Board

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: [No Variations]



	BOARD #: PMP10215	REV: B	SUN REV: Not In VersionControl
PCB VIEWED FROM BOTTOM SIDE	TID #: .TID	Board Outline	
PLOT NAME = Assembly Bottom	GENERATED : 4/26/2016	10:38:39 AM	TEXAS INSTRUMENTS

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